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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	H8/300H
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, SCI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	29
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN
Supplier Device Package	48-VQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/hd64f3694gftv

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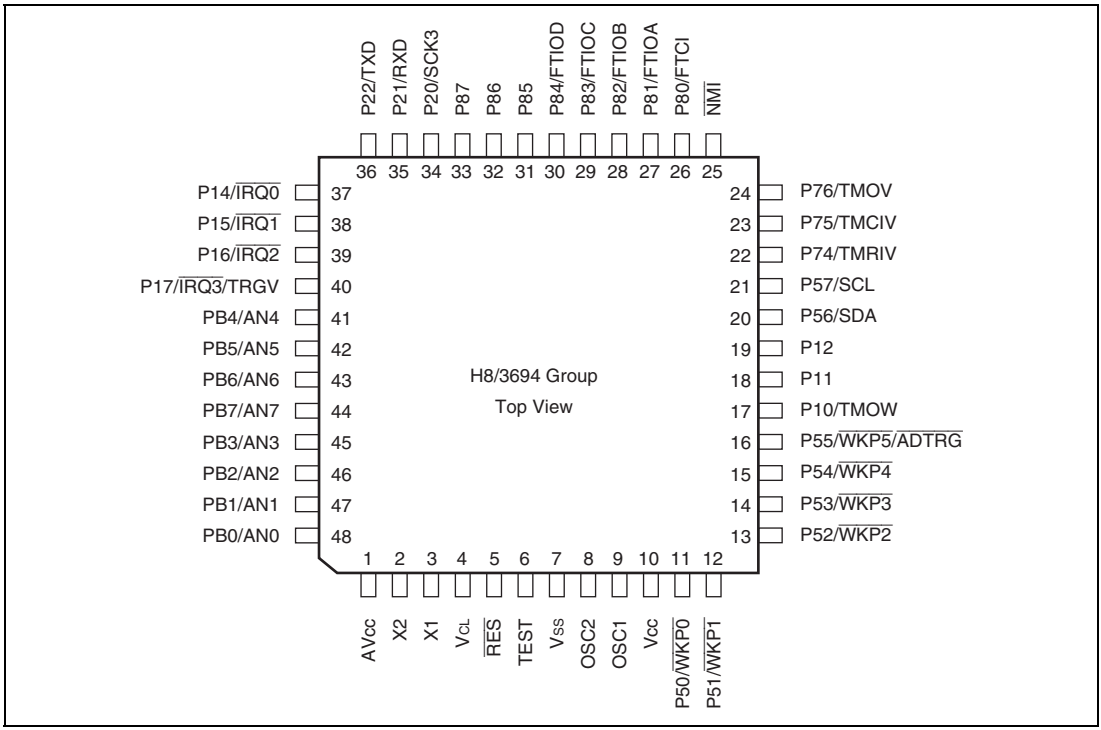


Figure 1.4 Pin Arrangement of H8/3694 Group of F-ZTAT™ and Mask-ROM Versions (FP-48F, FP-48B, TNP-48)

General register ER7 has the function of stack pointer (SP) in addition to its general-register function, and is used implicitly in exception handling and subroutine calls. Figure 2.4 shows the relationship between stack pointer and the stack area.

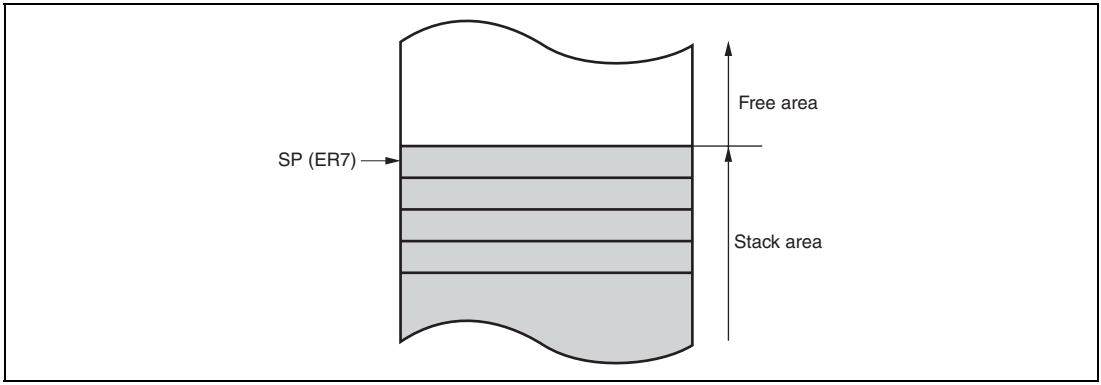


Figure 2.4 Relationship between Stack Pointer and Stack Area

2.2.2 Program Counter (PC)

This 24-bit counter indicates the address of the next instruction the CPU will execute. The length of all CPU instructions is 2 bytes (one word), so the least significant PC bit is ignored. (When an instruction is fetched, the least significant PC bit is regarded as 0). The PC is initialized when the start address is loaded by the vector address generated during reset exception-handling sequence.

2.2.3 Condition-Code Register (CCR)

This 8-bit register contains internal CPU status information, including an interrupt mask bit (I) and half-carry (H), negative (N), zero (Z), overflow (V), and carry (C) flags. The I bit is initialized to 1 by reset exception-handling sequence, but other bits are not initialized.

Some instructions leave flag bits unchanged. Operations can be performed on the CCR bits by the LDC, STC, ANDC, ORC, and XORC instructions. The N, Z, V, and C flags are used as branching conditions for conditional branch (Bcc) instructions.

For the action of each instruction on the flag bits, see appendix A.1, Instruction List.

Table 2.4 Logic Operations Instructions

Instruction	Size*	Function
AND	B/W/L	Rd ∧ Rs → Rd, Rd ∧ #IMM → Rd Performs a logical AND operation on a general register and another general register or immediate data.
OR	B/W/L	Rd ∨ Rs → Rd, Rd ∨ #IMM → Rd Performs a logical OR operation on a general register and another general register or immediate data.
XOR	B/W/L	Rd ⊕ Rs → Rd, Rd ⊕ #IMM → Rd Performs a logical exclusive OR operation on a general register and another general register or immediate data.
NOT	B/W/L	¬ (Rd) → (Rd) Takes the one's complement (logical complement) of general register contents.

Note: * Refers to the operand size.
B: Byte
W: Word
L: Longword

Table 2.5 Shift Instructions

Instruction	Size*	Function
SHAL SHAR	B/W/L	Rd (shift) → Rd Performs an arithmetic shift on general register contents.
SHLL SHLR	B/W/L	Rd (shift) → Rd Performs a logical shift on general register contents.
ROTL ROTR	B/W/L	Rd (rotate) → Rd Rotates general register contents.
ROTXL ROTXR	B/W/L	Rd (rotate) → Rd Rotates general register contents through the carry flag.

Note: * Refers to the operand size.
B: Byte
W: Word
L: Longword

2.7 CPU States

There are four CPU states: the reset state, program execution state, program halt state, and exception-handling state. The program execution state includes active mode and subactive mode. For the program halt state there are a sleep mode, standby mode, and sub-sleep mode. These states are shown in figure 2.11. Figure 2.12 shows the state transitions. For details on program execution state and program halt state, refer to section 6, Power-Down Modes. For details on exception processing, refer to section 3, Exception Handling.

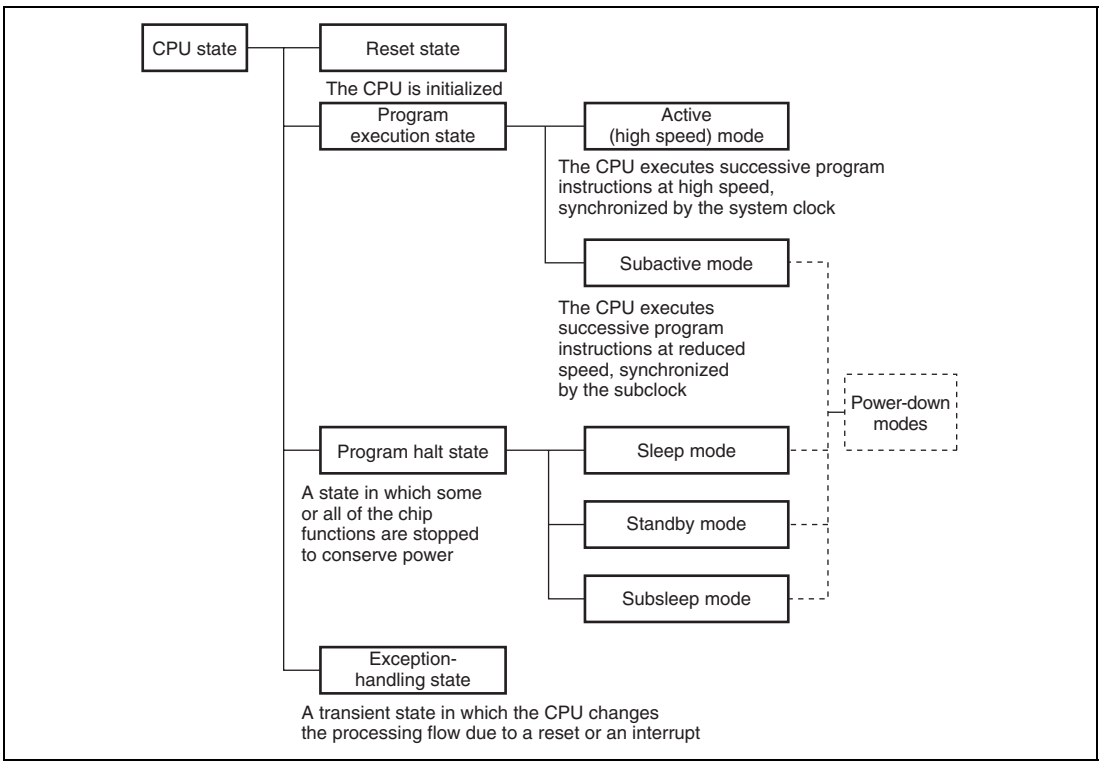


Figure 2.11 CPU Operation States

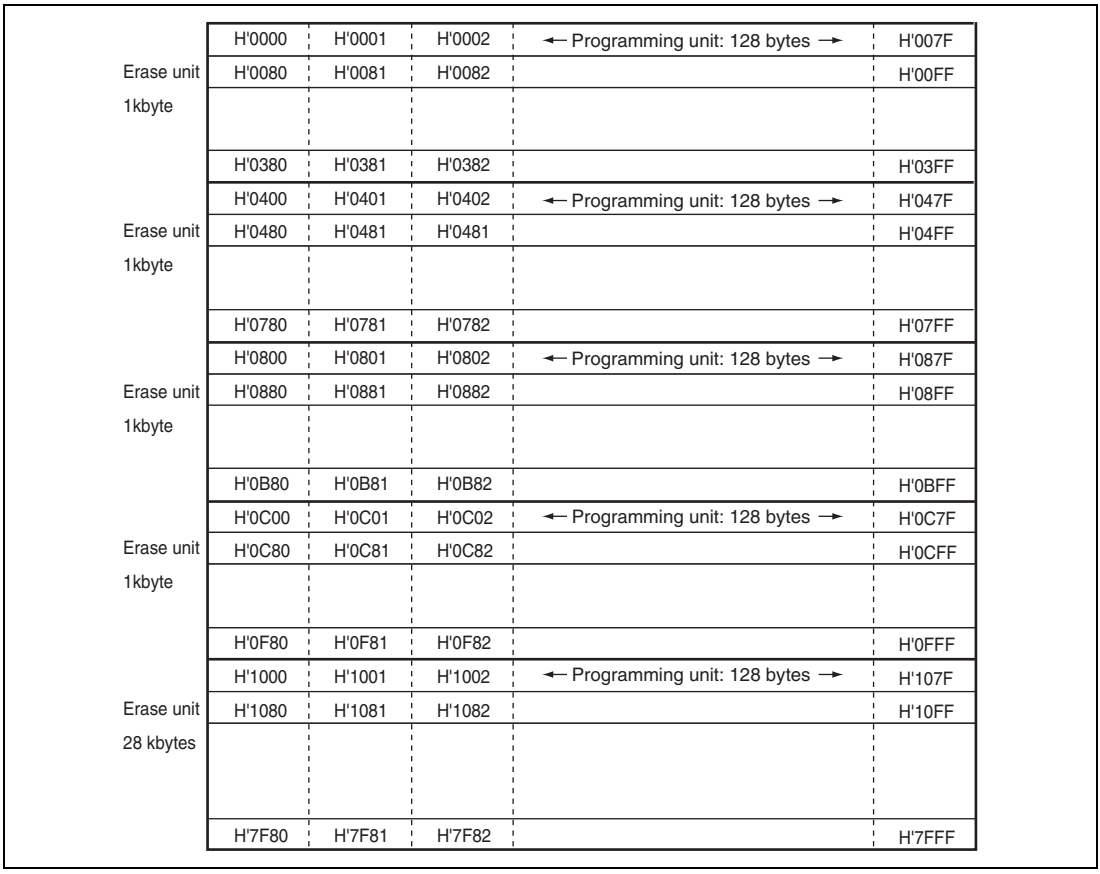


Figure 7.1 Flash Memory Block Configuration

7.2 Register Descriptions

The flash memory has the following registers.

- Flash memory control register 1 (FLMCR1)
- Flash memory control register 2 (FLMCR2)
- Erase block register 1 (EBR1)
- Flash memory power control register (FLPWCR)
- Flash memory enable register (FENR)

P15/$\overline{\text{IRQ1}}$ pin

Register	PMR1	PCR1	
Bit Name	**IRQ1**	**PCR15**	**Pin Function**
Setting value	0	0	P15 input pin
		1	P15 output pin
	1	X	$\overline{\text{IRQ1}}$ input pin

Legend: X: Don't care.

P14/$\overline{\text{IRQ0}}$ pin

Register	PMR1	PCR1	
Bit Name	**IRQ0**	**PCR14**	**Pin Function**
Setting value	0	0	P14 input pin
		1	P14 output pin
	1	X	$\overline{\text{IRQ0}}$ input pin

Legend: X: Don't care.

P12 pin

Register	PCR1	
Bit Name	**PCR12**	**Pin Function**
Setting value	0	P12 input pin
	1	P12 output pin

P11 pin

Register	PCR1	
Bit Name	**PCR11**	**Pin Function**
Setting value	0	P11 input pin
	1	P11 output pin

Section 14 Serial Communication Interface 3 (SCI3)

Serial Communication Interface 3 (SCI3) can handle both asynchronous and clocked synchronous serial communication. In the asynchronous method, serial data communication can be carried out using standard asynchronous communication chips such as a Universal Asynchronous Receiver/Transmitter (UART) or an Asynchronous Communication Interface Adapter (ACIA). A function is also provided for serial communication between processors (multiprocessor communication function).

Figure 14.1 shows a block diagram of the SCI3.

14.1 Features

- Choice of asynchronous or clocked synchronous serial communication mode
- Full-duplex communication capability

  The transmitter and receiver are mutually independent, enabling transmission and reception to be executed simultaneously.

  Double-buffering is used in both the transmitter and the receiver, enabling continuous transmission and continuous reception of serial data.
- On-chip baud rate generator allows any bit rate to be selected
- External clock or on-chip baud rate generator can be selected as a transfer clock source.
- Six interrupt sources

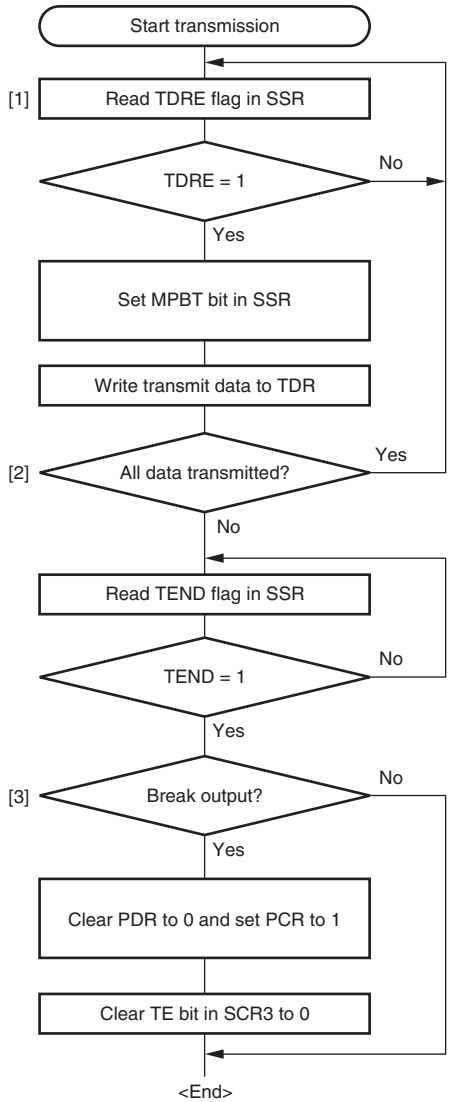
  Transmit-end, transmit-data-empty, receive-data-full, overrun error, framing error, and parity error.

Asynchronous mode

- Data length: 7 or 8 bits
- Stop bit length: 1 or 2 bits
- Parity: Even, odd, or none
- Receive error detection: Parity, overrun, and framing errors
- Break detection: Break can be detected by reading the RxD pin level directly in the case of a framing error

Clocked synchronous mode

- Data length: 8 bits
- Receive error detection: Overrun errors detected



[1] Read SSR and check that the TDRE flag is set to 1, set the MPBT bit in SSR to 0 or 1, then write transmit data to TDR. When data is written to TDR, the TDRE flag is automatically cleared to 0.

[2] To continue serial transmission, be sure to read 1 from the TDRE flag to confirm that writing is possible, then write data to TDR. When data is written to TDR, the TDRE flag is automatically cleared to 0.

[3] To output a break in serial transmission, set the port PCR to 1, clear PDR to 0, then clear the TE bit in SCR3 to 0.

Figure 14.16 Sample Multiprocessor Serial Transmission Flowchart

R/$\overline{W}$: Indicates the direction of data transfer: from the slave device to the master device when R/$\overline{W}$ is 1, or from the master device to the slave device when R/$\overline{W}$ is 0.
A: Acknowledge. The receive device drives SDA to low.
DATA: Transfer data
P: Stop condition. The master device drives SDA from low to high while SCL is high.

15.4.2 Master Transmit Operation

In master transmit mode, the master device outputs the transmit clock and transmit data, and the slave device returns an acknowledge signal. For master transmit mode operation timing, refer to figures 15.5 and 15.6. The transmission procedure and operations in master transmit mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MLS and WAIT bits in ICMR and the CKS3 to CKS0 bits in ICCR1 to 1. (Initial setting)
2. Read the BBSY flag in ICCR2 to confirm that the bus is free. Set the MST and TRS bits in ICCR1 to select master transmit mode. Then, write 1 to BBSY and 0 to SCP using MOV instruction. (Start condition issued) This generates the start condition.
3. After confirming that TDRE in ICSR has been set, write the transmit data (the first byte data show the slave address and R/$\overline{W}$) to ICDRT. At this time, TDRE is automatically cleared to 0, and data is transferred from ICDRT to ICDRS. TDRE is set again.
4. When transmission of one byte data is completed while TDRE is 1, TEND in ICSR is set to 1 at the rise of the 9th transmit clock pulse. Read the ACKBR bit in ICIER, and confirm that the slave device has been selected. Then, write second byte data to ICDRT. When ACKBR is 1, the slave device has not been acknowledged, so issue the stop condition. To issue the stop condition, write 0 to BBSY and SCP using MOV instruction. SCL is fixed low until the transmit data is prepared or the stop condition is issued.
5. The transmit data after the second byte is written to ICDRT every time TDRE is set.
6. Write the number of bytes to be transmitted to ICDRT. Wait until TEND is set (the end of last byte data transmission) while TDRE is 1, or wait for NACK (NACKF in ICSR = 1) from the receive device while ACKE in ICIER is 1. Then, issue the stop condition to clear TEND or NACKF.
7. When the STOP bit in ICSR is set to 1, the operation returns to the slave receive mode.

Table 16.3 A/D Conversion Time (Single Mode)

		CKS = 0			CKS = 1		
Item	**Symbol**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**
A/D conversion start delay time	t_D	6	—	9	4	—	5
Input sampling time	t_{SPL}	—	31	—	—	15	—
A/D conversion time	t_{CONV}	131	—	134	69	—	70

Note: All values represent the number of states.

16.4.4 External Trigger Input Timing

A/D conversion can also be started by an external trigger input. When the TRGE bit in ADCR is set to 1, external trigger input is enabled at the $\overline{\text{ADTRG}}$ pin. A falling edge at the $\overline{\text{ADTRG}}$ input pin sets the ADST bit in ADCSR to 1, starting A/D conversion. Other operations, in both single and scan modes, are the same as when the bit ADST has been set to 1 by software. Figure 16.3 shows the timing.

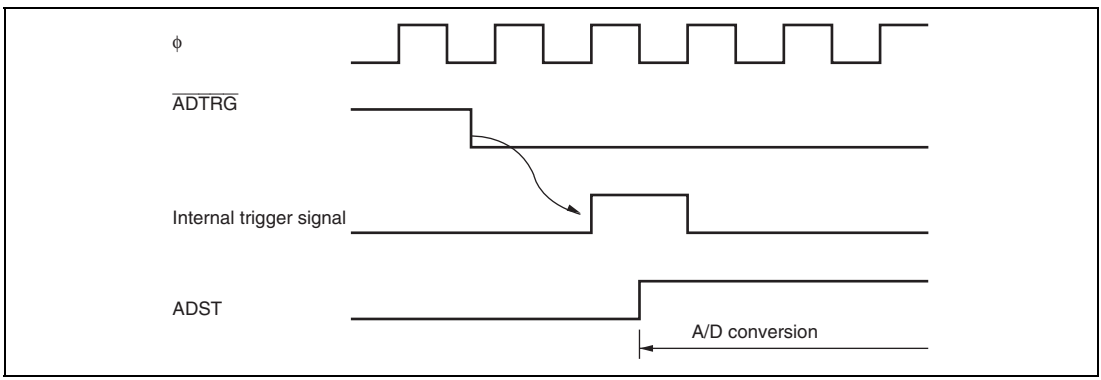


Figure 16.3 External Trigger Input Timing

16.6 Usage Notes

16.6.1 Permissible Signal Source Impedance

This LSI's analog input is designed such that conversion accuracy is guaranteed for an input signal for which the signal source impedance is 5 kΩ or less. This specification is provided to enable the A/D converter's sample-and-hold circuit input capacitance to be charged within the sampling time; if the sensor output impedance exceeds 5 kΩ, charging may be insufficient and it may not be possible to guarantee A/D conversion accuracy. However, for A/D conversion in single mode with a large capacitance provided externally, the input load will essentially comprise only the internal input resistance of 10 kΩ, and the signal source impedance is ignored. However, as a low-pass filter effect is obtained in this case, it may not be possible to follow an analog signal with a large differential coefficient (e.g., 5 mV/µs or greater) (see figure 16.6). When converting a high-speed analog signal or converting in scan mode, a low-impedance buffer should be inserted.

16.6.2 Influences on Absolute Accuracy

Adding capacitance results in coupling with GND, and therefore noise in GND may adversely affect absolute accuracy. Be sure to make the connection to an electrically stable GND.

Care is also required to ensure that filter circuits do not interfere with digital signals or act as antennas on the mounting board.

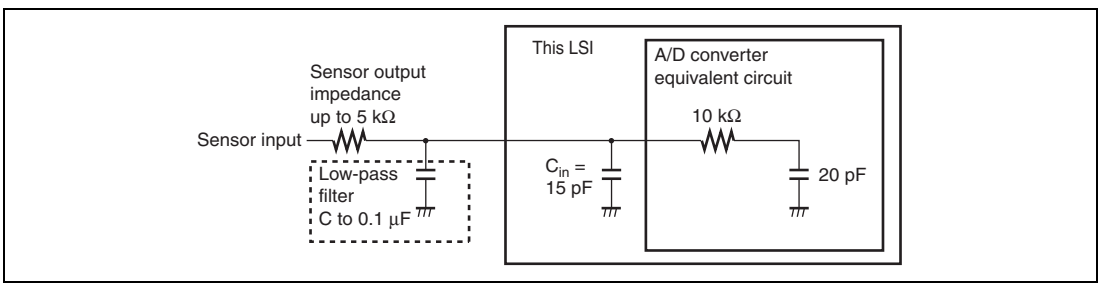


Figure 16.6 Analog Input Circuit Example

17.4.4 Stop Condition

A low-to-high transition of the SDA input with the SCL input high is needed to generate the stop condition for stopping read, write operation.

The standby operation starts after a read sequence by a stop condition. In the case of write operation, a stop condition terminates the write data inputs and place the device in an internally-timed write cycle to the memories. After the internally-timed write cycle (t_{WC}) which is specified as t_{WC}, the device enters a standby mode.

17.4.5 Acknowledge

All address data and serial data such as read data and write data are transmitted to and from in 8-bit unit. The acknowledgement is the signal that indicates that this 8-bit data is normally transmitted to and from.

In the write operation, EEPROM sends "0" to acknowledge in the ninth cycle after receiving the data. In the read operation, EEPROM sends a read data following the acknowledgement after receiving the data. After sending read data, the EEPROM enters the bus open state. If the EEPROM receives "0" as an acknowledgement, it sends read data of the next address. If the EEPROM does not receive acknowledgement "0" and receives a following stop condition, it stops the read operation and enters a standby mode. If the EEPROM receives neither acknowledgement "0" nor a stop condition, the EEPROM keeps bus open without sending read data.

17.4.6 Slave Addressing

The EEPROM device receives a 7-bit slave address and a 1-bit R/$\overline{W}$ code following the generation of the start conditions. The EEPROM enables the chip for a read or a write operation with this operation.

The slave address consists of a former 4-bit device code and latter 3-bit slave address as shown in table 17.2. The device code is used to distinguish device type and this LSI uses "1010" fixed code in the same manner as in a general-purpose EEPROM. The slave address code selects one device out of all devices with device code 1010 (8 devices in maximum) which are connected to the I^2C bus. This means that the device is selected if the inputted slave address code received in the order of A2, A1, A0 is equal to the corresponding slave address reference register (ESAR).

The slave address code is stored in the address H'FF09 in the EEPROM. It is transferred to ESAR from the slave address register in the memory array during 10 ms after the reset is released. An access to the EEPROM is not allowed during transfer.

Section 19 Power Supply Circuit

This LSI incorporates an internal power supply step-down circuit. Use of this circuit enables the internal power supply to be fixed at a constant level of approximately 3.0 V, independently of the voltage of the power supply connected to the external V_{CC} pin. As a result, the current consumed when an external power supply is used at 3.0 V or above can be held down to virtually the same low level as when used at approximately 3.0 V. If the external power supply is 3.0 V or below, the internal voltage will be practically the same as the external voltage. It is, of course, also possible to use the same level of external power supply voltage and internal power supply voltage without using the internal power supply step-down circuit.

19.1 When Using Internal Power Supply Step-Down Circuit

Connect the external power supply to the V_{CC} pin, and connect a capacitance of approximately 0.1 µF between V_{CL} and V_{SS}, as shown in figure 19.1. The internal step-down circuit is made effective simply by adding this external circuit. In the external circuit interface, the external power supply voltage connected to V_{CC} and the GND potential connected to V_{SS} are the reference levels. For example, for port input/output levels, the V_{CC} level is the reference for the high level, and the V_{SS} level is that for the low level. The A/D converter analog power supply is not affected by the internal step-down circuit.

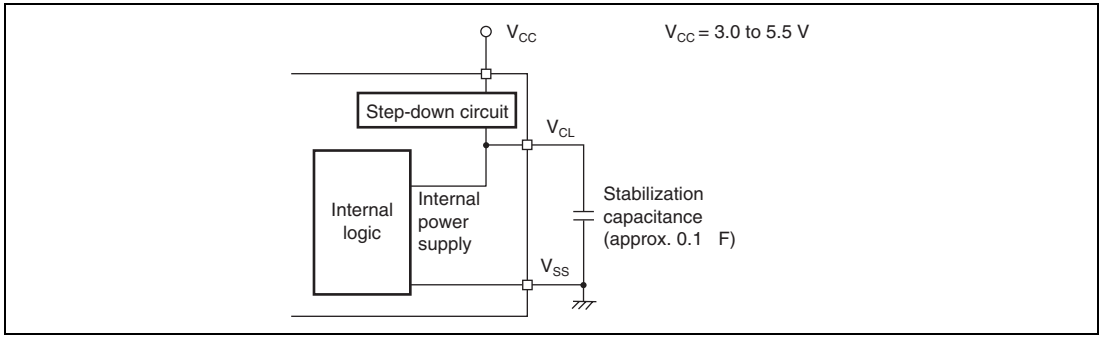


Figure 19.1 Power Supply Connection when Internal Step-Down Circuit is Used

Register Name	Abbre-viation	Bit No	Address	Module Name	Data Bus Width	Access State
A/D data register B	ADDRB	16	H'FFB2	A/D converter	8	3
A/D data register C	ADDRC	16	H'FFB4	A/D converter	8	3
A/D data register D	ADDRD	16	H'FFB6	A/D converter	8	3
A/D control/status register	ADCSR	8	H'FFB8	A/D converter	8	3
A/D control register	ADCR	8	H'FFB9	A/D converter	8	3
—	—	—	H'FFBA to H'FFBF	—	—	—
Timer control/status register WD	TCSRWD	8	H'FFC0	WDT*[3]	8	2
Timer counter WD	TCWD	8	H'FFC1	WDT*[3]	8	2
Timer mode register WD	TMWD	8	H'FFC2	WDT*[3]	8	2
—	—	—	H'FFC3	—	—	—
—	—	—	H'FFC4 to H'FFC7	—	—	—
Address break control register	ABRKCR	8	H'FFC8	Address break	8	2
Address break status register	ABRKSR	8	H'FFC9	Address break	8	2
Break address register H	BARH	8	H'FFCA	Address break	8	2
Break address register L	BARL	8	H'FFCB	Address break	8	2
Break data register H	BDRH	8	H'FFCC	Address break	8	2
Break data register L	BDRL	8	H'FFCD	Address break	8	2
—	—	—	H'FFCE, H'FFCF	—	—	—

Item	Symbol	Applicable Pins	Test Condition	Values Min	Values Typ	Values Max	Unit	Reference Figure
Input pin high width	t_{IH}	$\overline{NMI}$, $\overline{IRQ0}$ to $\overline{IRQ3}$, $\overline{WKP0}$ to $\overline{WKP5}$, TMCIV, TMRIV, TRGV, $\overline{ADTRG}$, FTCI, FTIOA to FTIOD		2	—	—	t_{cyc} t_{subcyc}	Figure 21.3
Input pin low width	t_{IL}	$\overline{NMI}$, $\overline{IRQ0}$ to $\overline{IRQ3}$, $\overline{WKP0}$ to $\overline{WKP5}$, TMCIV, TMRIV, TRGV, $\overline{ADTRG}$, FTCI, FTIOA to FTIOD		2	—	—	t_{cyc} t_{subcyc}	

Notes: 1 When an external clock is input, the minimum system clock oscillation frequency is 1.0 MHz.

2. Determined by MA2, MA1, MA0, SA1, and SA0 of system control register 2 (SYSCR2).

Mnemonic		Operand Size	Addressing Mode and Instruction Length (bytes)									Operation	Condition Code						No. of States*1	
			#xx	Rn	@ERn	@(d, ERn)	@–ERn/@ERn+	@aa	@(d, PC)	@@aa	—		I	H	N	Z	V	C	Normal	Advanced
BLD	BLD #xx:3, @ERd	B			4							(#xx:3 of @ERd) → C	—	—	—	—	—	↕	6	
	BLD #xx:3, @aa:8	B						4				(#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BILD	BILD #xx:3, Rd	B		2								¬ (#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BILD #xx:3, @ERd	B			4							¬ (#xx:3 of @ERd) → C	—	—	—	—	—	↕	6	
	BILD #xx:3, @aa:8	B						4				¬ (#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BST	BST #xx:3, Rd	B		2								C → (#xx:3 of Rd8)	—	—	—	—	—	—	2	
	BST #xx:3, @ERd	B			4							C → (#xx:3 of @ERd24)	—	—	—	—	—	—	8	
	BST #xx:3, @aa:8	B						4				C → (#xx:3 of @aa:8)	—	—	—	—	—	—	8	
BIST	BIST #xx:3, Rd	B		2								¬ C → (#xx:3 of Rd8)	—	—	—	—	—	—	2	
	BIST #xx:3, @ERd	B			4							¬ C → (#xx:3 of @ERd24)	—	—	—	—	—	—	8	
	BIST #xx:3, @aa:8	B						4				¬ C → (#xx:3 of @aa:8)	—	—	—	—	—	—	8	
BAND	BAND #xx:3, Rd	B		2								C∧(#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BAND #xx:3, @ERd	B			4							C∧(#xx:3 of @ERd24) → C	—	—	—	—	—	↕	6	
	BAND #xx:3, @aa:8	B						4				C∧(#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BIAND	BIAND #xx:3, Rd	B		2								C∧ ¬ (#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BIAND #xx:3, @ERd	B			4							C∧ ¬ (#xx:3 of @ERd24) → C	—	—	—	—	—	↕	6	
	BIAND #xx:3, @aa:8	B						4				C∧ ¬ (#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BOR	BOR #xx:3, Rd	B		2								C∨(#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BOR #xx:3, @ERd	B			4							C∨(#xx:3 of @ERd24) → C	—	—	—	—	—	↕	6	
	BOR #xx:3, @aa:8	B						4				C∨(#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BIOR	BIOR #xx:3, Rd	B		2								C∨ ¬ (#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BIOR #xx:3, @ERd	B			4							C∨ ¬ (#xx:3 of @ERd24) → C	—	—	—	—	—	↕	6	
	BIOR #xx:3, @aa:8	B						4				C∨ ¬ (#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BXOR	BXOR #xx:3, Rd	B		2								C⊕(#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BXOR #xx:3, @ERd	B			4							C⊕(#xx:3 of @ERd24) → C	—	—	—	—	—	↕	6	
	BXOR #xx:3, @aa:8	B						4				C⊕(#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	
BIXOR	BIXOR #xx:3, Rd	B		2								C⊕ ¬ (#xx:3 of Rd8) → C	—	—	—	—	—	↕	2	
	BIXOR #xx:3, @ERd	B			4							C⊕ ¬ (#xx:3 of @ERd24) → C	—	—	—	—	—	↕	6	
	BIXOR #xx:3, @aa:8	B						4				C⊕ ¬ (#xx:3 of @aa:8) → C	—	—	—	—	—	↕	6	

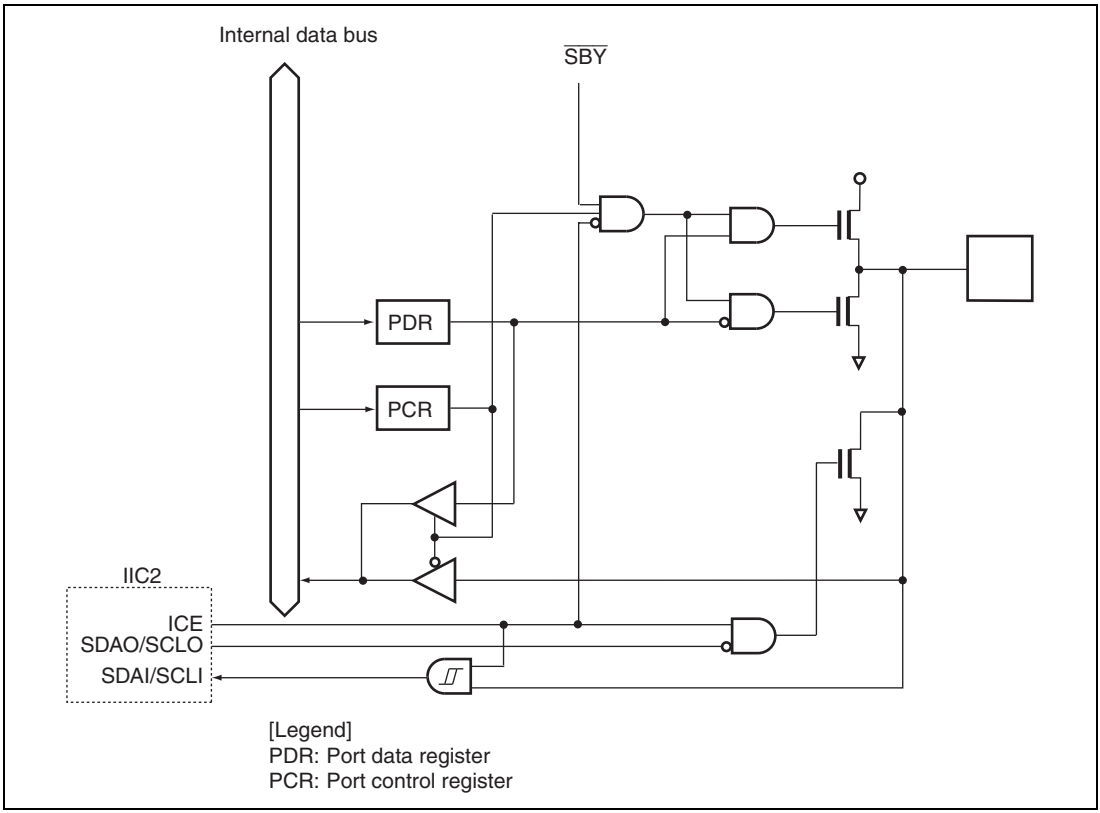


Figure B.8 Port 5 Block Diagram (P57, P56)*

Note: * This diagram is applied to the SCL and SDA pins in the H8/3694N.

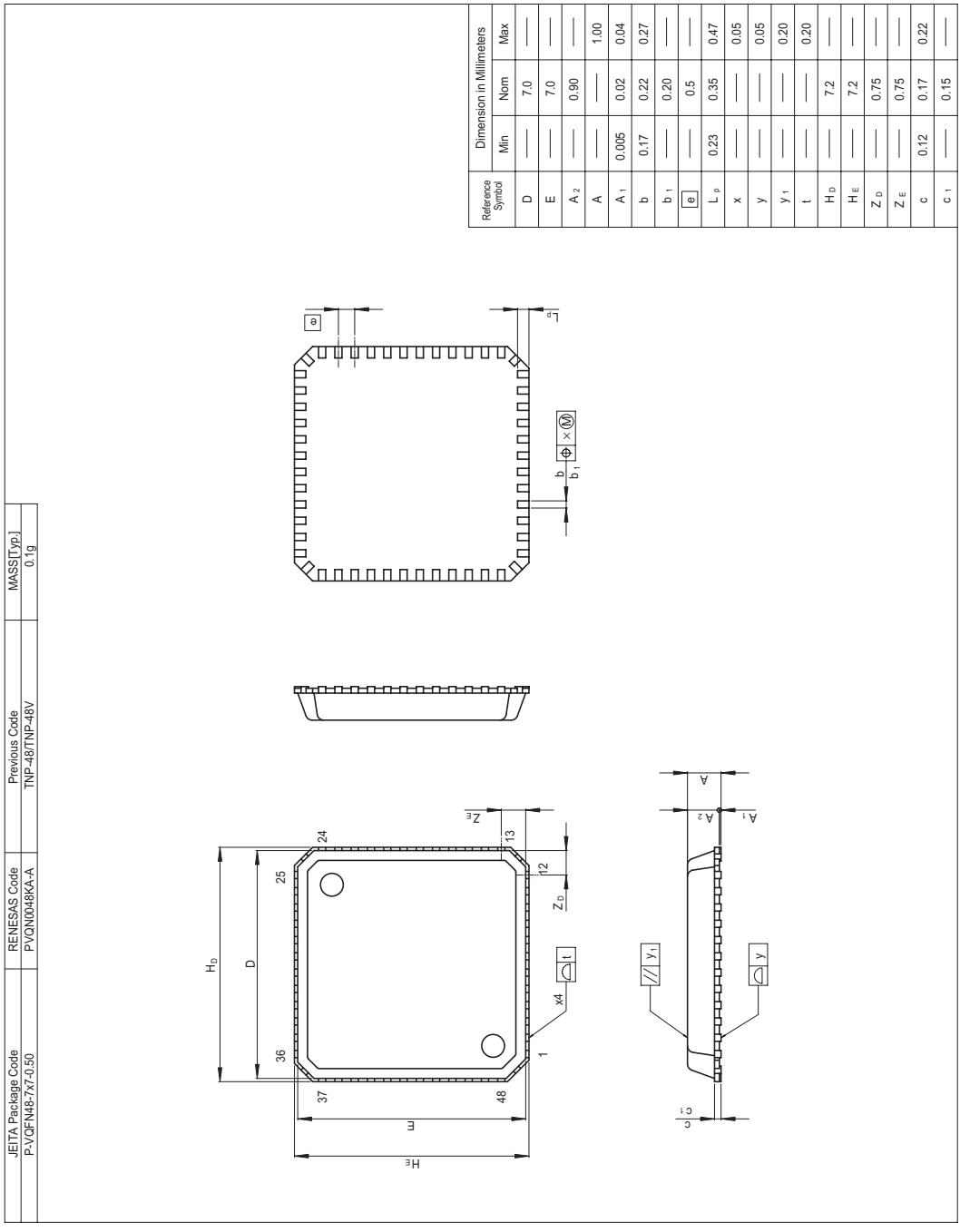


Figure D.5 TNP-48 Package Dimensions